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II. **Fabrication and Feasibility of Through Silicon Via for 3D MEMS Resonator Integration**

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III. **Multi-channel thin film piezoelectric acoustic transducer for cochlear implant applications**

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IV. **A Pulse-Width Modulated Cochlear Implant Interface Electronics with 513  $\mu$ W Power Consumption**

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## **Metrikler**

Yayın: 9

Atf (WoS): 25

Atf (Scopus): 31

H-İndeks (WoS): 4

H-İndeks (Scopus): 4